

REL22CX LEAD-FREE SOLDER TOP-OFF ALLOY

FEATURES

- For use with AIM REL22™ Alloy to Reduce Copper Levels
- Available in Solder Bar and Chunk
- Manufactured using AIM Electropure® Processes

DESCRIPTION

AIM's REL22CX alloy is used to correct and maintain the copper content of REL22 alloy in wave and selective soldering applications. REL22CX is composed of key constituents of REL22 with lower copper levels.

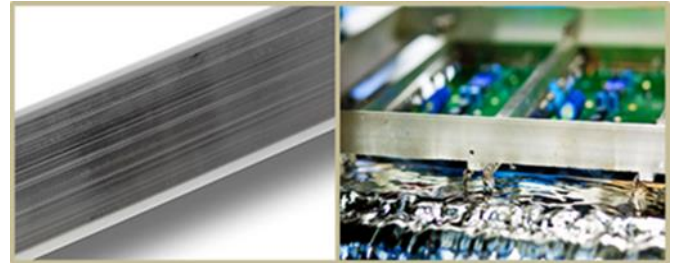
PROCESS

REL22 alloy copper levels may increase due to copper dissolved from PCB and components leads. Excess copper content can adversely impact the performance of REL22, increasing the incidence of bridges, icicles and other defects. Replenishing solder with REL22CX will maintain copper content at recommended levels. AIM Solder analysis should be performed monthly to monitor and control solder bath within specified limits.

SOLDER POT ANALYSIS

| Take Action Limits (TAL) | | |
|--------------------------|----------|-----------|
| Ag: 4.0 | Au: 0.2 | Al: 0.06 |
| As: 0.03 | Bi: 3.0 | Cd: 0.01 |
| Cu: 1.1 | Fe: 0.05 | Ni: 0.1 |
| Pb: 0.1 | Sb: 0.9 | Zn: 0.006 |

Take Action Limits (TAL) are intended to provide users with upper limits of alloy impurities while material is in use. TAL are established by AIM and are IPC J-STD-001 compliant. These guidelines may be adjusted to achieve specific product performance requirements.



HANDLING & STORAGE

| Parameter | Time | Temperature |
|------------|------------|------------------|
| Shelf Life | Indefinite | Room Temperature |

Solid alloy solder products have an indefinite shelf life when proper storage conditions are observed. Consult the SDS for additional handling procedures.

AVAILABILITY

REL22CX is available in bar and solder chunk. Other formats may be available upon request.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying SDS for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.